



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jiang et al.

Serial No.: 09/483,712

Filed: January 14, 2000

For: METHOD OF FABRICATING CHIP-
SCALE PACKAGES AND RESULTING
STRUCTURES

Examiner: M. Warren

Group Art Unit: 2815

Attorney Docket No.: 3815US (98-0670)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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**PRELIMINARY AMENDMENT AND
RESPONSE TO RESTRICTION REQUIREMENT**

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicants herein acknowledge the restriction requirement in the above-referenced application. Applicants hereby elect the claims of Group I, claims 1 through 20, without traverse.

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.